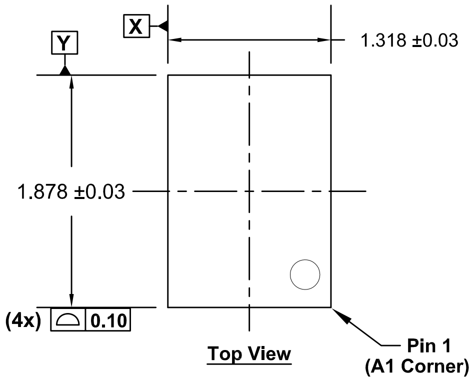
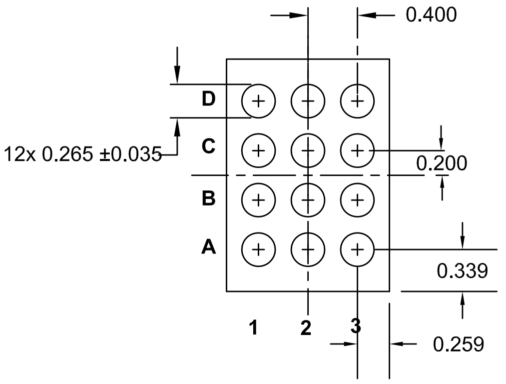
Package Outline Drawing

W3x4.12D

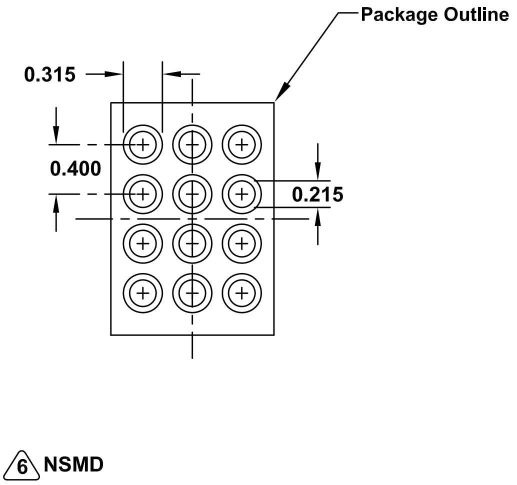
12 Ball Wafer Level Chip Scale Package (WLCSP 0.4mm Pitch)
Rev 1, 9/2022



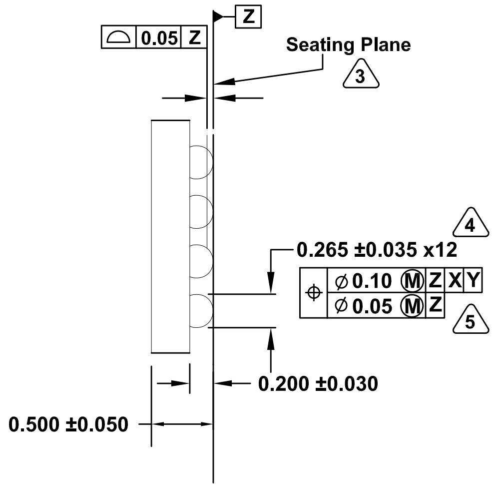
Top View



Bottom View



Recommended Land Pattern



Side View

NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerances per ASME Y14.5-1994.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
5. Bump position designation per JESD 95-1, SPP-010.
6. NSMD refers to non-solder mask defined pad design per TB451.